



TECHNICAL DATA SHEET

Sn63Pb37 Solder Sticks

PRODUCT DESCRIPTION

PAI Sn63Pb37 solder sticks are being formulated with virgin raw metals processed in state-of-the-art Vacuum Technology that brings world class quality along. Here, oxygen interaction with alloy is nil and thus, dross formation is reduced at PCB assembly or PCB manufacturing processes. Also an increased flow rate & reduced impurities found. PAI Sn63Pb37 is compatible with typical range of flux application formulas used in Electronics Industry today.

STORAGE AND HANDLING

- Do not use fire near storage area.
- Store in dry, cool and non-corrosive environment.
- Wear Personal Protective Equipments while handling.
- Wear Personal Protective Equipments while processing.

ALLOY COMPOSITION

Sl. No	Metal	PAI Sn63Pb37 Solder Sticks	ISO9453 Specification	J-STD-006 Specification
1	Sn	63% min	62.5%~63.50%	62.5%~63.50%
2	Pb	Rem	Rem	Rem
3	Sb	0.05% max	0.05% max	0.5% max
4	Cu	0.05% max	0.05% max	0.08% max
5	Au	0.05% max	0.05% max	NA
6	Ag	0.10% max	NA	0.10% max
7	Al	0.001% max	0.001% max	0.005% max
8	As	0.03% max	0.03% max	0.03% max
9	Bi	0.05% max	0.05% max	0.25% max
10	Cd	0.002% max	0.002% max	0.001% max
11	In	0.003% max	NA	NA
12	Fe	0.02% max	0.02% max	0.02% max
13	Ni	0.01% max	NA	0.01% max
14	Zn	0.001% max	0.001% max	0.003% max
15	S	0.0004% max	NA	NA



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PHYSICAL CHARACTERISTICS OF APPLICATION

Alloy	Sn63Pb37
Shape	Rectangular
Density	8.4gm/cm ³ at 20 ⁰ C
Melting Point	183 ⁰ C
Standard Package Quantity	25Kgs
Application	Wave Soldering / HASL Process
Standards Considered	JIS-Z-3282
Shelf Life	10 Years

TECHNICAL SPECIFICATIONS

Technical Factors Recommended	Specifications
Solder Pot Temperature	250°C to 260°C
Dwell Time	2 Sec to 4 Sec
Immersion	0.5% to 0.70% of PWBs thickness that being processed
Dross Recovery	Once in every 8 hours
Impurities Level Check	In-house specifications
Other Factors	Refer liquid flux manufacturer specifications for desired yields

Note: The recommendations stated above have been contributed for desired Solder Joints and shall modify if required based on the end user Specifications.

For more details, please visit Our Website at www.persangalloy.com or write to us.



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